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## 2019 International Conference on Advanced Electronic Materials, Computers and Materials Engineering (AEMCME 2019)

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## Preface

This issue of Proceedings gathers the papers presented at 2019 2nd International Conference on Advanced Electronic Materials, Computers and Materials Engineering (AEMCME 2019) held on April 19-21, 2019 in Changsha, China. AEMCME is an international conference covering research and development in the field of advanced electronic materials and computers and allow the participation from all over the world.

More than 500 papers were submitted on the conference, and AEMCME finally accepted 316 papers after a double blinded peer review process by international reviewers and technical program committee members. Divided into 4 chapters, the papers provide a wide spectrum of researches on wide range of advanced electronic materials and computers. The chapters are devoted to Materials Engineering, Mechanical Engineering, Computer Programming and Industrial Design, as well as Software Engineering and Algorithm. Specific research results by conference participants were presented and examined in the light of the frameworks outlined above, which is of interest to academics, researchers and professionals in this field.

Three keynote speeches were presented from Prof. Zhiqiang Hou, Xi'an University of Posts and Telecommunications, China; Prof. Zhezhaio Zeng, Changsha University of Science & Technology, China separately. All the talks were very impressive for the high level of professionalism, and in many cases original ideas and activities have been accomplished or proposed.

The credit for the success of the conference is to be shared with many colleagues. First and foremost, conference chairs, program chairs, conference technical committee members gave precious inputs and were always side by side with the organizers. We are also indebted to session chairs, international reviewers, conference secretariat who dedicated to make the conference run smoothly and properly, and ensure the proceedings quality. Last but not the least, we should express our thanks to all delegates, who showing the high level of international interest in the subject. It is exactly your participation that make the conference to its success.

The Proceedings provide the permanent record of what were presented. It indicated the state of development at the time of writing of all aspects of this important topic and will be invaluable to all researchers in the field for that reason. We truly believe the participants will find the discussion fruitful, and we hope you enjoy and find your engagement with their ideas valuable in sustaining your own professional development in the field of measurement instrumentation and electronics.

Prof. T. A. Hwee

Chairman of AEMCME 2019 conference



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